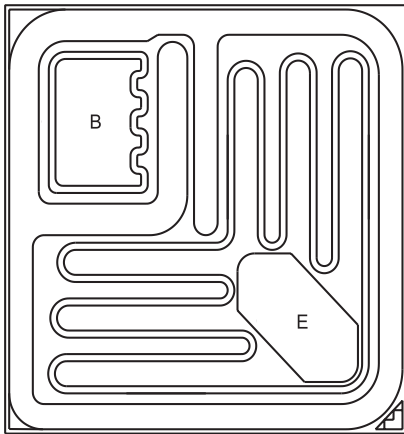


**PROCESS DETAILS**

Process	EPITAXIAL BASE
Die Size	111 X 111 MILS
Die Thickness	10 MILS
Base Bonding Pad Area	20 X 30 MILS
Emitter Bonding Pad Area	20 X 26 MILS
Top Side Metalization	Al - 30,000Å
Back Side Metalization	Au/Cr/Ni/Au - Ni-6,000Å, Au-6,000Å

**GEOMETRY**



BACKSIDE COLLECTOR

R1

**GROSS DIE PER 5 INCH WAFER**

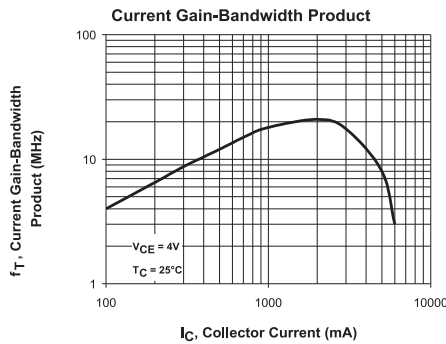
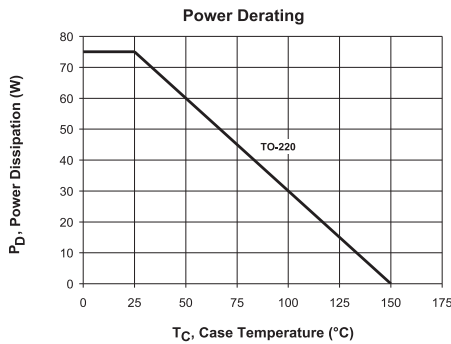
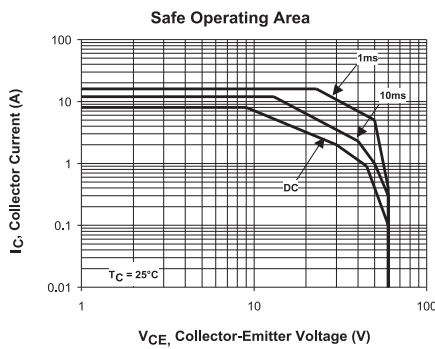
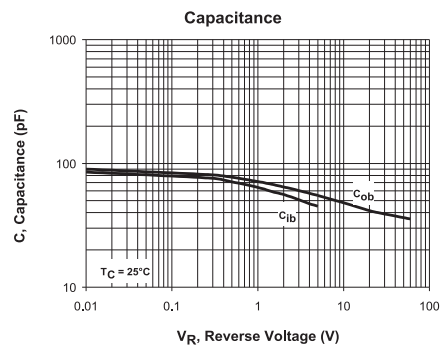
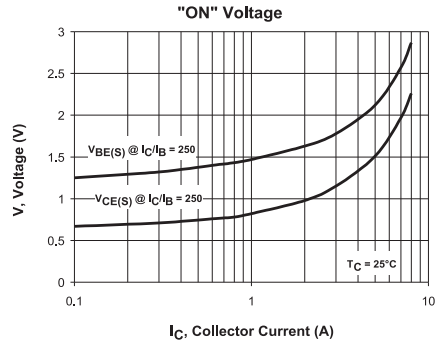
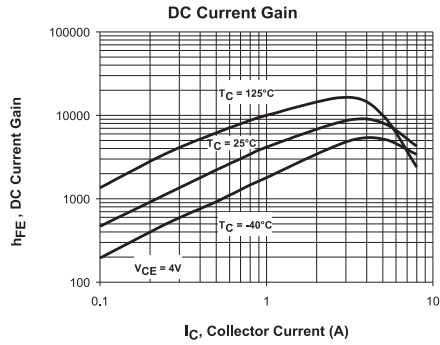
910

**PRINCIPAL DEVICE TYPES**

- 2N6043
- 2N6044
- 2N6045
- 2N6301

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